

HM62V8100I Series

Wide Temperature Range Version

8 M SRAM (1024-kword × 8-bit)

ADE-203-1278B (Z)
Rev.2.00
Nov.02.2009

Description

The HM62V8100I Series is 8-Mbit static RAM organized 1,048,576-word × 8-bit. HM62V8100I Series has realized higher density, higher performance and low power consumption by employing Hi-CMOS process technology. It offers low power standby power dissipation; therefore, it is suitable for battery backup systems. It is packaged package with 0.75 mm bump pitch or standard 44-pin TSOP II for high density surface mounting.

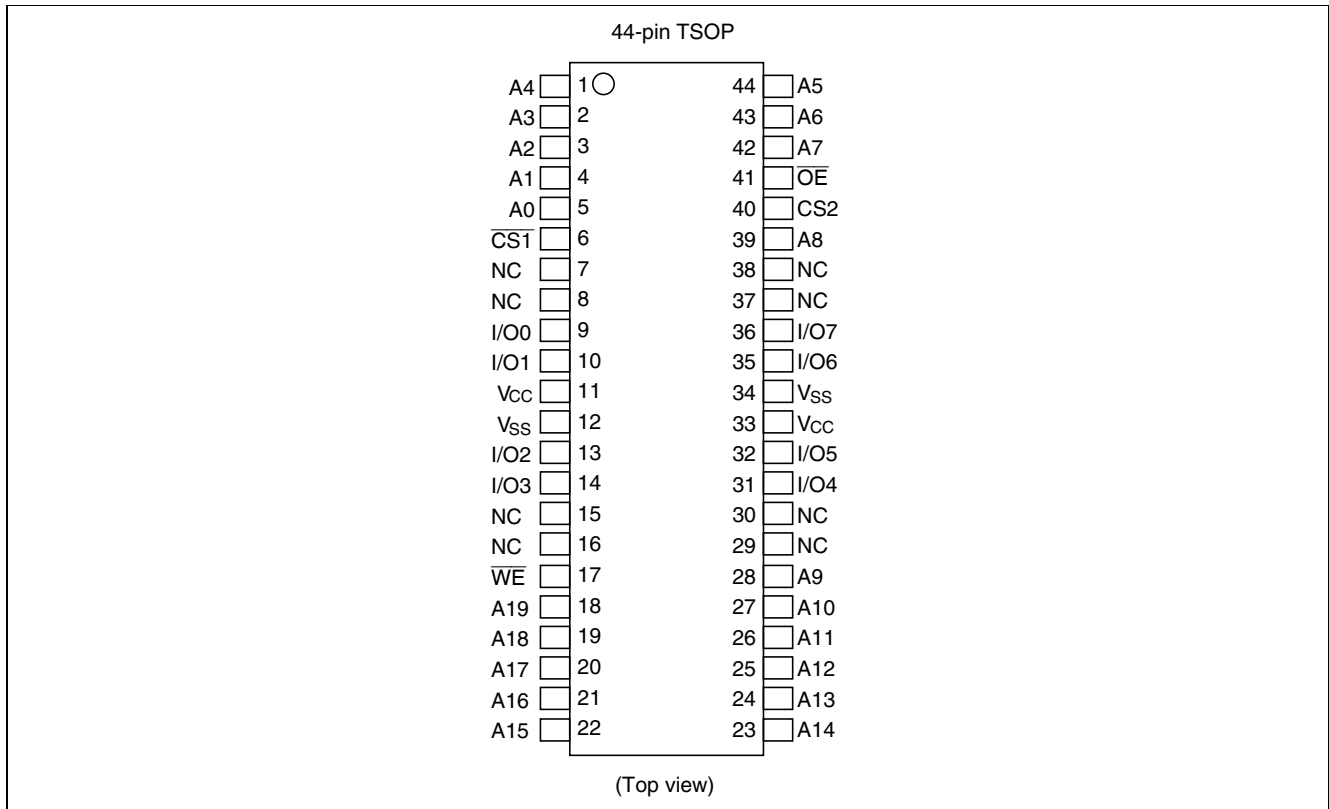
Features

- Single 3.0 V supply: 2.7 V to 3.6 V
- Fast access time: 55 ns (Max)
- Power dissipation:
 - Active: 6.0 mW/MHz (Typ)
 - Standby: 1.5 μ W (Typ)
- Completely static memory.
 - No clock or timing strobe required
- Equal access and cycle times
- Common data input and output.
 - Three state output
- Battery backup operation.
 - 2 chip selection for battery backup
- Temperature range: -40 to +85°C

Ordering Information

Type No.	Access time	Package
HM62V8100LTTI-5	55 ns	400-mil 44pin plastic TSOP II (normal-bend type) (TTP-44DE)
HM62V8100LTTI-5SL	55 ns	

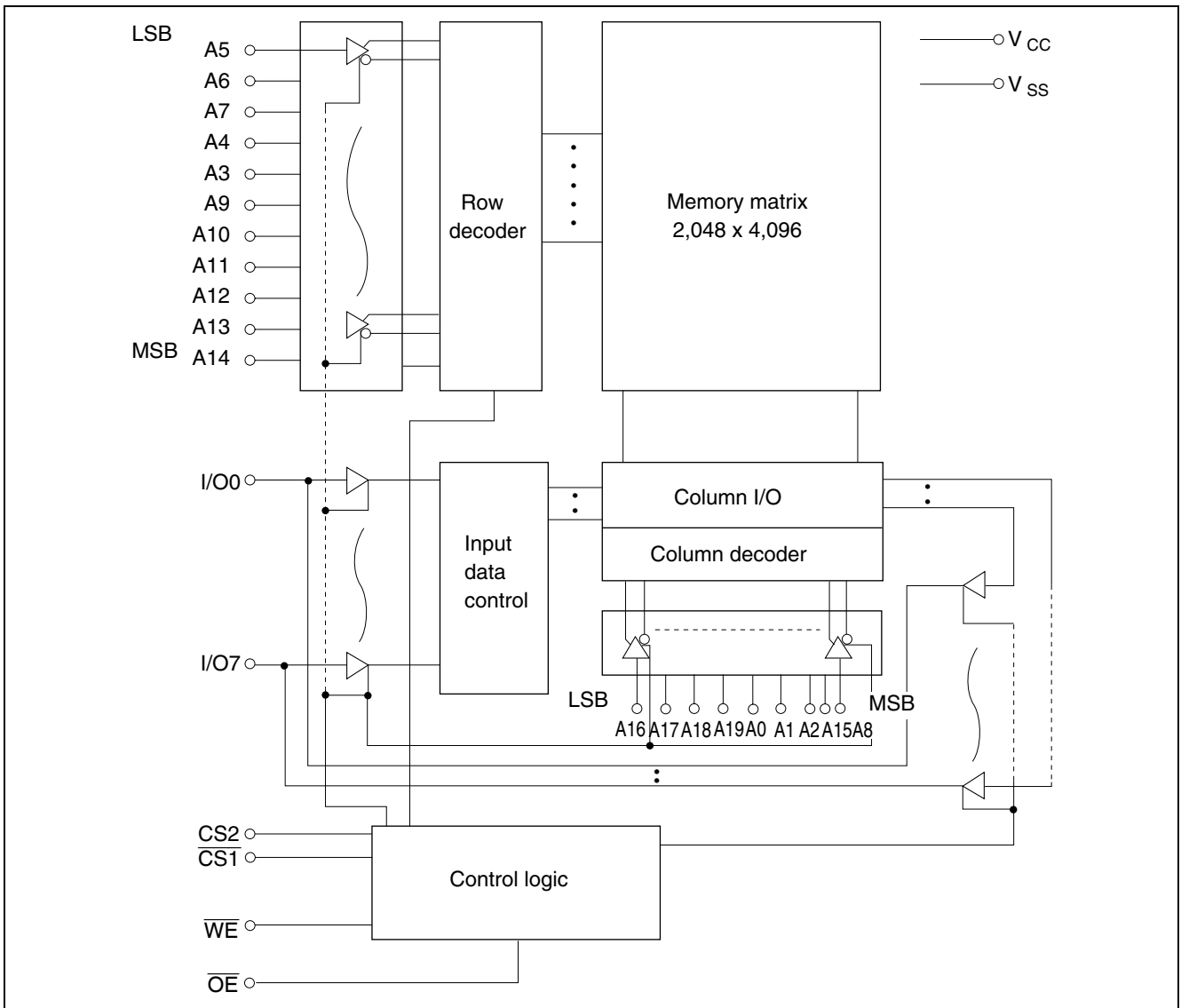
Pin Arrangement



Pin Description

Pin name	Function
A0 to A19	Address input
I/O0 to I/O7	Data input/output
$\overline{CS1}$	Chip select 1
CS2	Chip select 2
\overline{WE}	Write enable
\overline{OE}	Output enable
V _{cc}	Power supply
V _{ss}	Ground
NC	No connection

Block Diagram



Operation Table

$\overline{CS1}$	CS2	\overline{WE}	\overline{OE}	I/O0 to I/O7	Operation
H	x	x	x	High-Z	Standby
x	L	x	x	High-Z	Standby
L	H	H	L	Dout	Read
L	H	L	x	Din	Write
L	H	H	H	High-Z	Output disable

Note: H: V_{IH} , L: V_{IL} , x: V_{IH} or V_{IL}

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Power supply voltage relative to V_{SS}	V_{CC}	-0.5 to +4.6	V
Terminal voltage on any pin relative to V_{SS}	V_T	-0.5* ¹ to $V_{CC} + 0.3$ * ²	V
Power dissipation	P_T	1.0	W
Storage temperature range	Tstg	-55 to +125	°C
Storage temperature range under bias	Tbias	-40 to +85	°C

Notes: 1. V_T min: -3.0 V for pulse half-width \leq 30 ns.
2. Maximum voltage is +4.6 V.

DC Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Note
Supply voltage	V_{CC}	2.7	3.0	3.6	V	
	V_{SS}	0	0	0	V	
Input high voltage	V_{IH}	2.2	—	$V_{CC} + 0.3$	V	
Input low voltage	V_{IL}	-0.3	—	0.6	V	1
Ambient temperature range	T_a	-40	—	85	°C	

Note: 1. V_{IL} min: -3.0 V for pulse half-width \leq 30 ns.

DC Characteristics

Parameter	Symbol	Min	Typ* ¹	Max	Unit	Test conditions
Input leakage current	$ I_{Li} $	—	—	1	μA	$V_{in} = V_{SS} \text{ to } V_{CC}$
Output leakage current	$ I_{Lo} $	—	—	1	μA	$\overline{CS1} = V_{IH} \text{ or } CS2 = V_{IL} \text{ or } \overline{OE} = V_{IH} \text{ or } \overline{WE} = V_{IL}, \text{ or } V_{I/O} = V_{SS} \text{ to } V_{CC}$
Operating current	I_{CC}	—	—	20	mA	$\overline{CS1} = V_{IL}, CS2 = V_{IH}, \text{ Others} = V_{IH}/V_{IL}, I_{I/O} = 0 \text{ mA}$
Average operating current	I_{CC1}	—	14	25	mA	Min. cycle, duty = 100%, $I_{I/O} = 0 \text{ mA}, \overline{CS1} = V_{IL}, CS2 = V_{IH}, \text{ Others} = V_{IH}/V_{IL}$
	I_{CC2}	—	2	4	mA	Cycle time = 1 μs , duty = 100%, $I_{I/O} = 0 \text{ mA}, \overline{CS1} \leq 0.2 \text{ V}, CS2 \geq V_{CC} - 0.2 \text{ V}, V_{IH} \geq V_{CC} - 0.2 \text{ V}, V_{IL} \leq 0.2 \text{ V}$
Standby current	I_{SB}	—	0.1	0.3	mA	$CS2 = V_{IL}$
Standby current	I_{SB1}^{*2}	—	0.5	25	μA	$0 \text{ V} \leq V_{in}$ (1) $0 \text{ V} \leq CS2 \leq 0.2 \text{ V}$ or (2) $\overline{CS1} \geq V_{CC} - 0.2 \text{ V}, CS2 \geq V_{CC} - 0.2 \text{ V}$
	I_{SB1}^{*3}	—	0.5	10	μA	
Output high voltage	V_{OH}	2.2	—	—	V	$I_{OH} = -1 \text{ mA}$
Output low voltage	V_{OL}	—	—	0.4	V	$I_{OL} = 2 \text{ mA}$

Note: 1. Typical values are at $V_{CC} = 3.0 \text{ V}$, $T_a = +25^\circ\text{C}$ and not guaranteed.
 2. This characteristic is guaranteed only for L version.
 3. This characteristic is guaranteed only for L-SL version.

Capacitance ($T_a = +25^\circ\text{C}$, $f = 1.0 \text{ MHz}$)

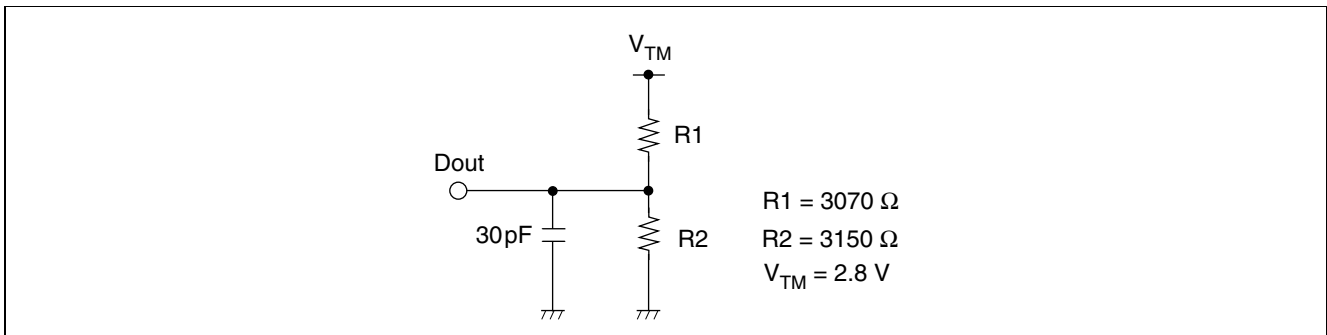
Parameter	Symbol	Min	Typ	Max	Unit	Test conditions	Note
Input capacitance	C_{in}	—	—	8	pF	$V_{in} = 0 \text{ V}$	1
Input/output capacitance	$C_{I/O}$	—	—	10	pF	$V_{I/O} = 0 \text{ V}$	1

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = -40 to +85°C, VCC = 2.7 V to 3.6 V, unless otherwise noted.)

Test Conditions

- Input pulse levels: $V_{IL} = 0.4\text{ V}$, $V_{IH} = 2.2\text{ V}$
- Input rise and fall time: 5 ns
- Input and output timing reference levels: 1.5 V
- Output load: See figures (Including scope and jig)



Read Cycle

Parameter	Symbol	HM62V8100I		Unit	Notes
		Min	Max		
Read cycle time	t_{RC}	55	—	ns	
Address access time	t_{AA}	—	55	ns	
Chip select access time	t_{ACS1}	—	55	ns	
	t_{ACS2}	—	55	ns	
Output enable to output valid	t_{OE}	—	35	ns	
Output hold from address change	t_{OH}	10	—	ns	
Chip select to output in low-Z	t_{CLZ1}	10	—	ns	2, 3
	t_{CLZ2}	10	—	ns	2, 3
Output enable to output in low-Z	t_{OLZ}	5	—	ns	2, 3
Chip deselect to output in high-Z	t_{CHZ1}	0	20	ns	1, 2, 3
	t_{CHZ2}	0	20	ns	1, 2, 3
Output disable to output in high-Z	t_{OHZ}	0	20	ns	1, 2, 3

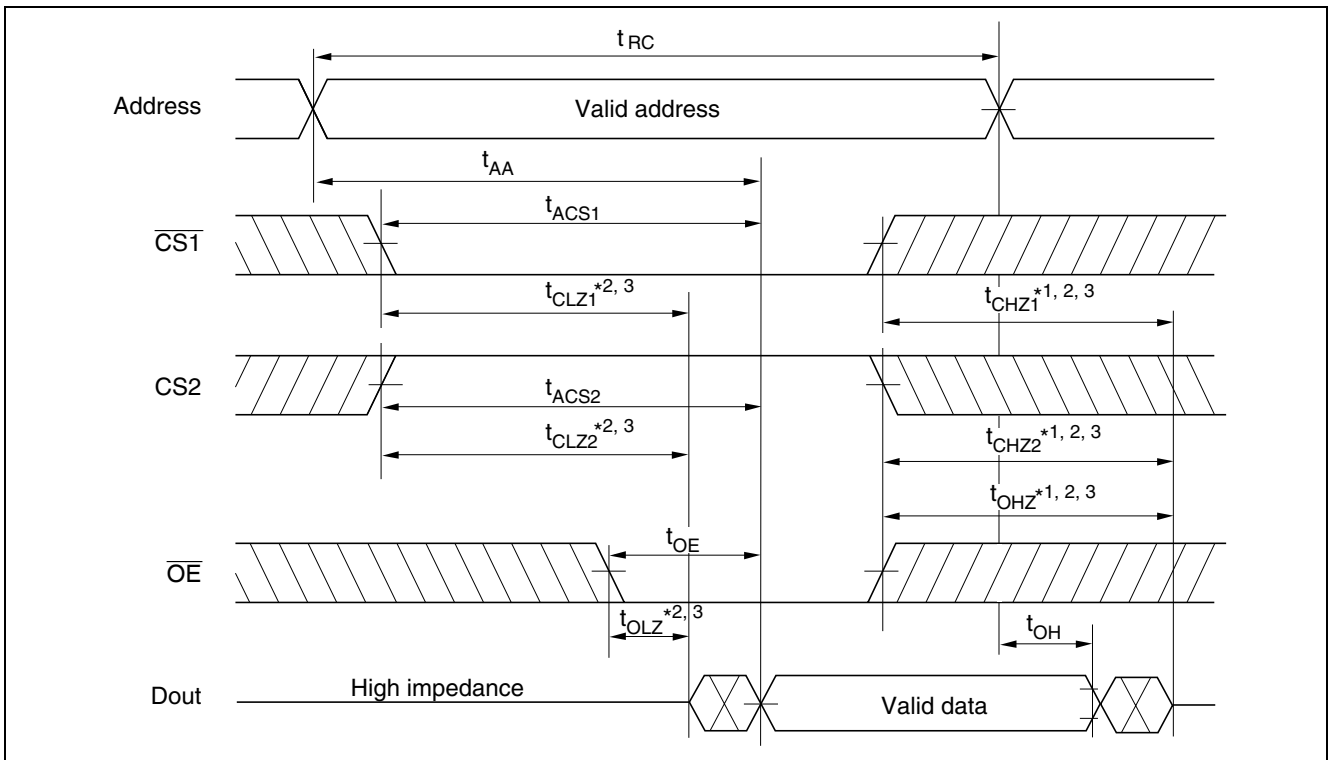
Write Cycle

Parameter	Symbol	HM62V8100I		Unit	Notes
		-5			
		Min	Max		
Write cycle time	t_{WC}	55	—	ns	
Address valid to end of write	t_{AW}	50	—	ns	
Chip selection to end of write	t_{CW}	50	—	ns	5
Write pulse width	t_{WP}	40	—	ns	4
Address setup time	t_{AS}	0	—	ns	6
Write recovery time	t_{WR}	0	—	ns	7
Data to write time overlap	t_{DW}	25	—	ns	
Data hold from write time	t_{DH}	0	—	ns	
Output active from end of write	t_{OW}	5	—	ns	2
Output disable to output in High-Z	t_{OHZ}	0	20	ns	1, 2
Write to output in high-Z	t_{WHZ}	0	20	ns	1, 2

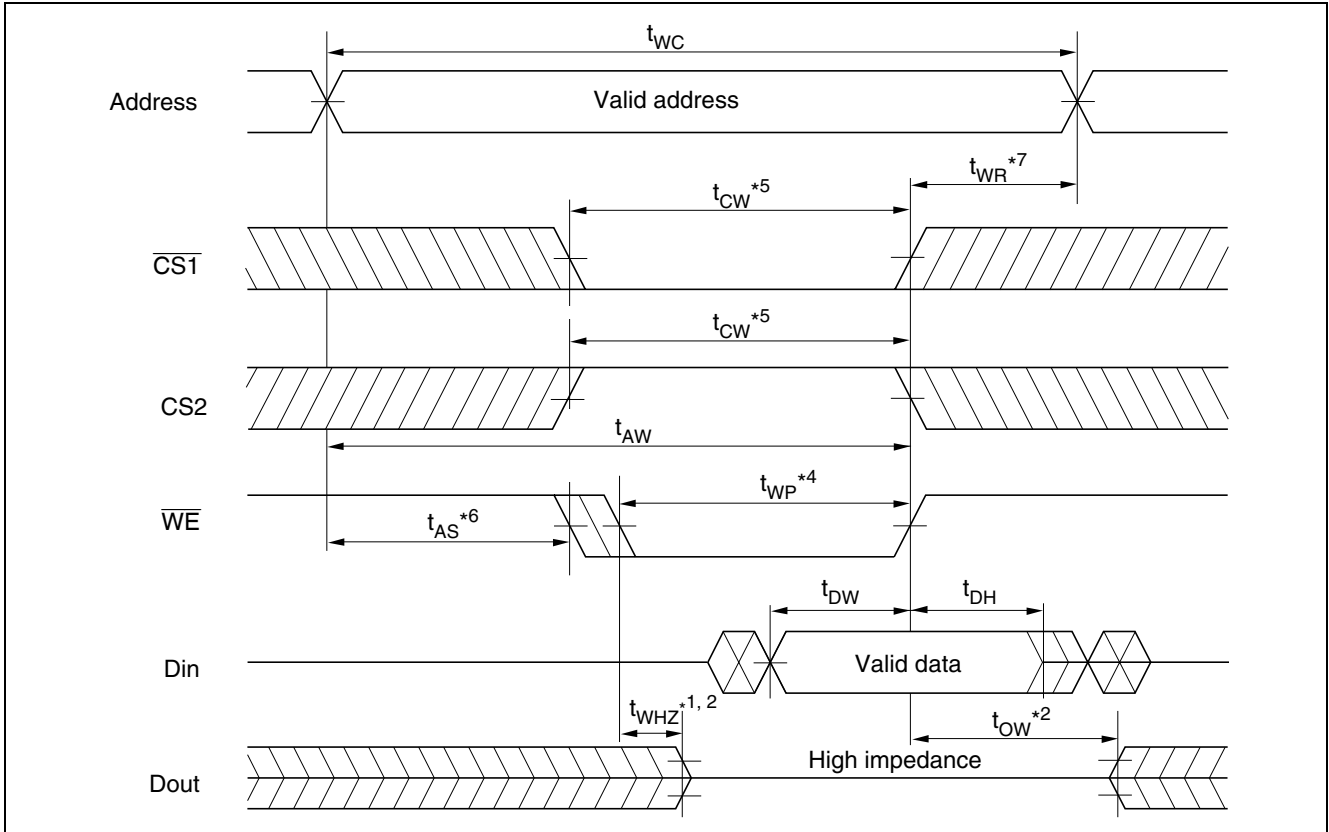
- Notes:
1. t_{CHZ} , t_{OHZ} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.
 2. This parameter is sampled and not 100% tested.
 3. At any given temperature and voltage condition, t_{HZ} max is less than t_{LZ} min both for a given device and from device to device.
 4. A write occurs during the overlap of a low $\overline{CS1}$, a high CS2, a low \overline{WE} . A write begins at the latest transition among $\overline{CS1}$ going low, CS2 going high, \overline{WE} going low. A write ends at the earliest transition among $\overline{CS1}$ going high, CS2 going low, \overline{WE} going high. t_{WP} is measured from the beginning of write to the end of write.
 5. t_{CW} is measured from the later of $\overline{CS1}$ going low or CS2 going high to the end of write.
 6. t_{AS} is measured from the address valid to the beginning of write.
 7. t_{WR} is measured from the earliest of $\overline{CS1}$ or \overline{WE} going high or CS2 going low to the end of write cycle.

Timing Waveform

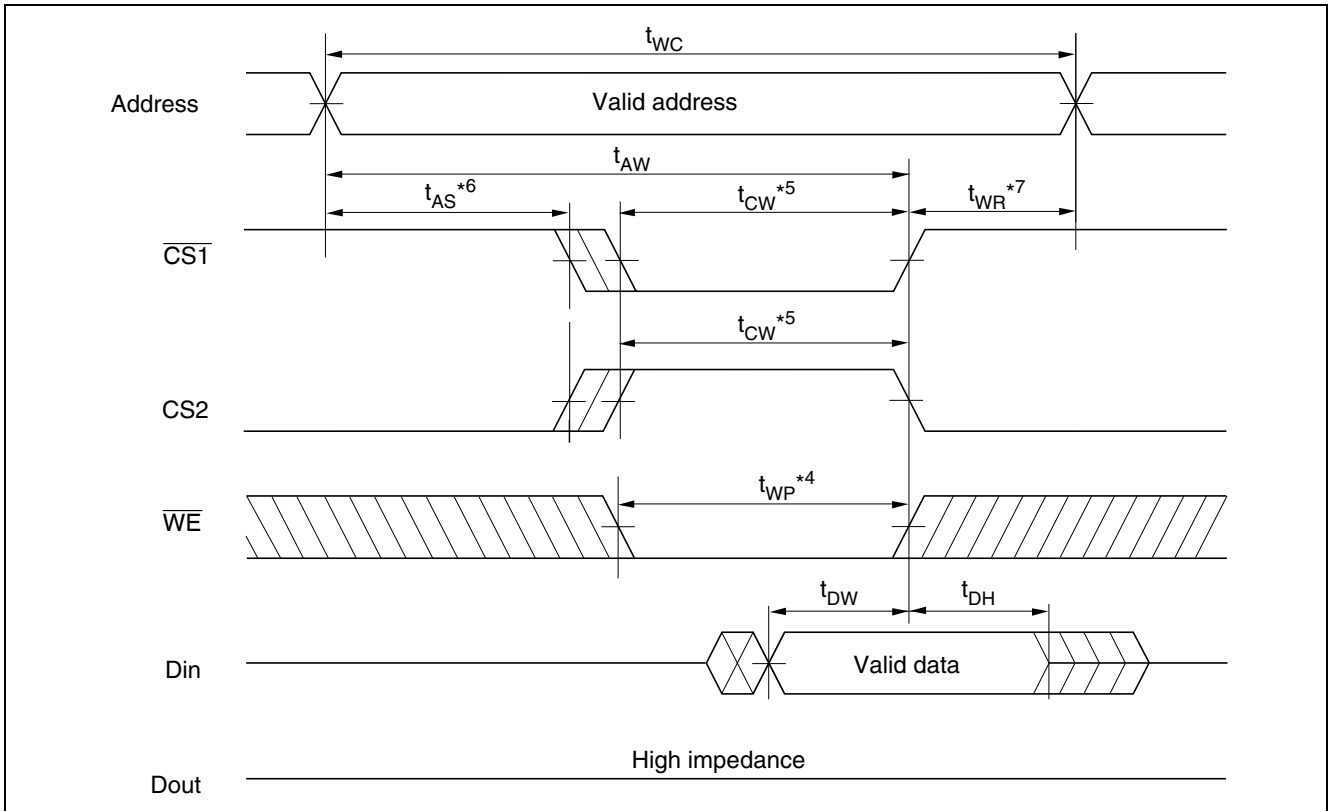
Read Cycle



Write Cycle (1) ($\overline{\text{WE}}$ Clock)



Write Cycle (2) (CS Clock, $\overline{OE} = VIH$)



Low VCC Data Retention Characteristics (Ta = -40 to +85°C)

Parameter	Symbol	Min	Typ ^{*4}	Max	Unit	Test conditions ^{*3}
V _{CC} for data retention	V _{DR}	2.0	—	3.6	V	V _{in} ≥ 0V (1) 0 V ≤ CS2 ≤ 0.2 V or (2) CS2 ≥ V _{CC} - 0.2 V $\overline{\text{CS1}} \geq V_{\text{CC}} - 0.2 \text{ V}$
Data retention current	I _{CCDR} ^{*1}	—	0.5	25	μA	V _{CC} = 3.0 V, V _{in} ≥ 0V (1) 0 V ≤ CS2 ≤ 0.2 V or (2) CS2 ≥ V _{CC} - 0.2 V, $\overline{\text{CS1}} \geq V_{\text{CC}} - 0.2 \text{ V}$
	I _{CCDR} ^{*2}	—	0.5	10	μA	
Chip deselect to data retention time	t _{CDR}	0	—	—	ns	See retention waveform
Operation recovery time	t _R	t _{RC} ^{*5}	—	—	ns	

Notes: 1. This characteristic is guaranteed only for L version.

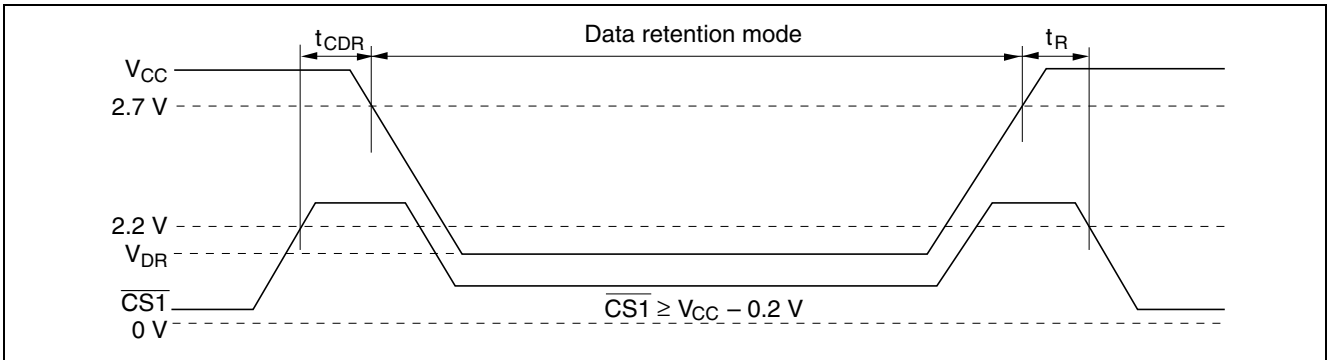
2. This characteristic is guaranteed only for L-SL version.

3. CS2 controls address buffer, $\overline{\text{WE}}$ buffer, $\overline{\text{CS1}}$ buffer, $\overline{\text{OE}}$ buffer and Din buffer. If CS2 controls data retention mode, V_{in} levels (address, $\overline{\text{WE}}$, $\overline{\text{OE}}$, $\overline{\text{CS1}}$, I/O) can be in the high impedance state. If $\overline{\text{CS1}}$ controls data retention mode, CS2 must be CS2 ≥ V_{CC} - 0.2 V or 0 V ≤ CS2 ≤ 0.2 V. The other input levels (address, $\overline{\text{WE}}$, $\overline{\text{OE}}$, I/O) can be in the high impedance state.

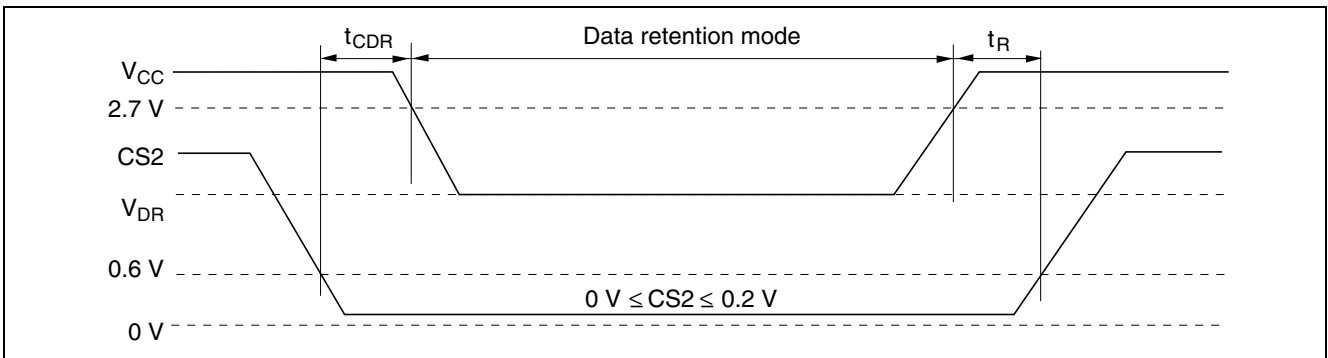
4. Typical values are at V_{CC} = 3.0 V, Ta = +25°C and not guaranteed.

5. t_{RC} = read cycle time.

Low VCC Data Retention Timing Waveform (1) ($\overline{CS1}$ Controlled)



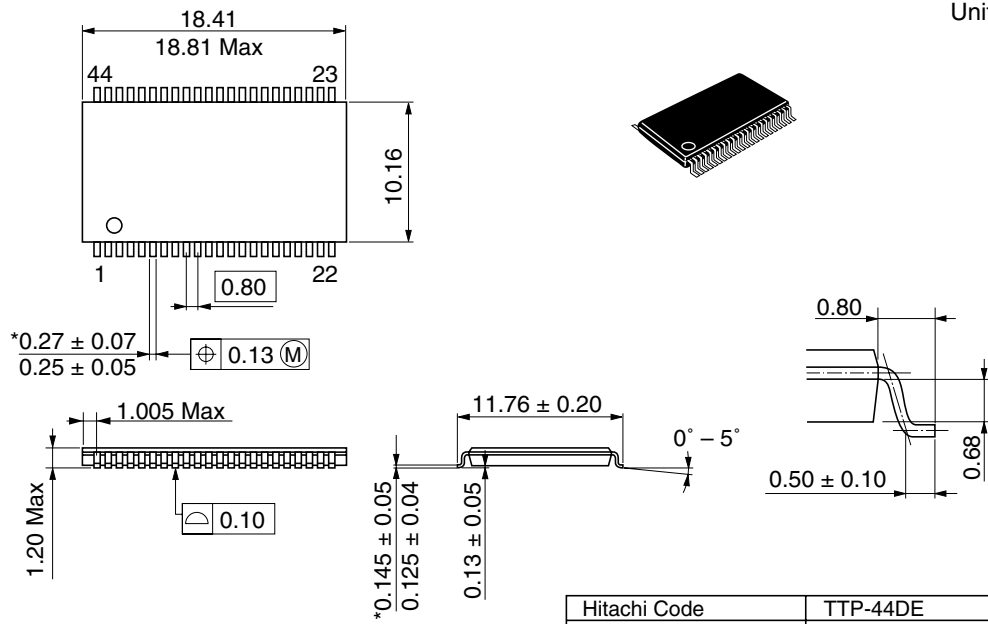
Low VCC Data Retention Timing Waveform (2) ($CS2$ Controlled)



Package Dimensions

HM62V8100LTTI Series (TTP-44DE)

As of July, 2001
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-44DE
JEDEC	—
JEITA	—
Mass (reference value)	0.43 g

Notes:

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